Customer Information Notification | 2015050111

Issue Date: 29-May-2015
Effective Date: 01-Jul-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

QUALITY

Management Summary
Gain binning will be skipped to create a more efficient and standard testflow omitting superfluous process steps. As a results the Gain binning will not be part anymore of the marking on the product.

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[X] Product Marking	[ ] Design
[ ] Wafer Fab materials	[ ] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Skip Gain binning

Information Notification

Gain binning was applied in the past on special customer request on a part of NXP portfolio. Necessity for Gain binning on a subset of this portfolio is not required anymore (see attached product list). Therefore the Gain binning step and associated marking on the affected products will be skipped. This will create a more efficient and standard testflow omitting superfluous process steps.

Why do we issue this Information Notification
To inform the customer on the change in product marking
Identification of Affected Products
Top side marking
Gain code will not be part anymore of the marking on the product.
Rest of the product marking will remain unchanged

Impact

no impact to the product's functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   Hans Buis
Position   Process Improvement manager
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest

possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC
BLF6G20LS-140,112	934060897112
BLF7G22LS-130,112	934063501112
BLF8G10LS-160,118	934065908118
BLF7G22LS-130,112	934063501112